11/28/00

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ZR SHEET



To: Honorable Commissioner of Patents and Trademarks:

	Please record the attached original document(s) or copy thereof.					
1.	Name of conveying party(ies) a) Anindya Poddar b) c) 9/724739					
2.	me and address of receiving party(ies): Name: National Semiconductor Corporation Address: 2900 Semiconductor Drive Sunnyvale, CA 95051					
3.	Nature of conveyance ☐ Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name ☐ Other ☐ License Agreement					
	Execution Date: November 28, 2000					
4.	Application Number(s) or Patent Number(s): Not Yet Assigned					
	The title of the (new) application is:					
	The title of the (new) application is: INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED D IN SINGLE-TIER EBGA PACKAGES					
5.	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED D					
5.	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED D IN SINGLE-TIER EBGA PACKAGES					
 6. 	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED DIN SINGLE-TIER EBGA PACKAGES Please send all correspondence concerning this (these) documents to: Customer Number: 022434 BEYER WEAVER & THOMAS, LLP P.O. Box 778 Berkeley, CA 94704-0778 Phone (650) 961-8300					
	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED DIN SINGLE-TIER EBGA PACKAGES Please send all correspondence concerning this (these) documents to: Customer Number: 022434 BEYER WEAVER & THOMAS, LLP P.O. Box 778 Berkeley, CA 94704-0778 Phone (650) 961-8300 Fax (650) 961-8301					
6.	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED DIN SINGLE-TIER EBGA PACKAGES Please send all correspondence concerning this (these) documents to: Customer Number: 022434 BEYER WEAVER & THOMAS, LLP P.O. Box 778 Berkeley, CA 94704-0778 Phone (650) 961-8300 Fax (650) 961-8301 Total number of applications and patents involved: 1					
6. 7. 8 .	INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED DIN SINGLE-TIER EBGA PACKAGES Please send all correspondence concerning this (these) documents to: Customer Number: 022434 BEYER WEAVER & THOMAS, LLP P.O. Box 778 Berkeley, CA 94704-0778 Phone (650) 961-8300 Fax (650) 961-8301 Total number of applications and patents involved: 1 Total fee (37 CFR 3.41): \$40.00 Enclosed Any additional fees are authorized to be charged to Deposit Account No. 500388					

Attorney Docket No. NSC1P190

02 FC:581

40.00 DP

(Revised 01/96)

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:

INTEGRATED CIRCUIT PACKAGE HAVING DIE WITH STAGGERED BOND PADS AND DIE PAD ASSIGNMENT METHODOLOGY FOR ASSEMBLY OF STAGGERED DIE IN SINGLE-TIER EBGA PACKAGES

(Atty. Docket No.: NSC1P190) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to <u>National Semiconductor Corporation</u>, a Delaware corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, California, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

1. Inventor Signature:	Anindya PODDAR	Person.		Date:	11/28/00
State of California County of Santa C	Jara)) ss)			
On this 28 personally known to mperson whose name is he/she executed the same the instrument the personal perso	day of November of Notary e (or proved to ne subscribed to the	within ins	trument, an	d acknow	wledged to me that his/her signature on
WITNESS my h Notary Signature	and and official so		NEAL)		ANGELIQUE M. BARBOA Commission # 1210949 Notary Public - California Los Angeles County My Comm. Expires Feb 14, 2003

Attorney Docket No.: NSC1P190/P04807

RECORDED: 11/28/2000

Page 1 of 1

PATENT REEL: 011319 FRAME: 0908